Product / Package Information

Package	TQFP
Body Size (mm)	7 X 7 X 1.0
Lead Count	64
Terminal Finish	100 Sn
MS Number	MS010619B

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	1.25E-01	88.00	880000	43.01	430144
Thermosets	Epoxy & Phenol Resin	Proprietary	1.64E-02	11.50	115000	5.62	56212
Other inorganic materials	Carbon black	1333-86-4	7.11E-04	0.50	5000	0.24	2444
Subtotal			1.42 E-01	100.00	1000000	48.88	488801

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.02 E-01	97.5	975000	35.02	350241
Copper & its alloys	Iron	7439-89-6	2.46 E-03	2.35	23500	0.84	8442
Copper & its alloys	Zinc	7440-66-6	1.25 E-04	0.12	1200	0.04	431
Copper & its alloys	Phosphorus	7723-14-0	3.14 E-05	0.03	300	0.01	108
Subtotal			1.05 E-01	100.00	1000000	35.92	359221

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	9.14 E-04	100.0	1000000	0.31	3140

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	6.23 E-03	100.0	1000000	2.14	21422

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	2.56 E-03	100.0	1000000	0.88	8792

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.95 E-02	100.0	1000000	10.15	101528

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	3.66 E-03	73.54	735400	1.26	12572
Other organic materials	Epoxy resin A	TS ref# 10013	3.66 E-04	7.35	73500	0.13	1257
Others	Anhydride	TS ref# 10181	3.66 E-04	7.35	73500	0.13	1257
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	1.46 E-04	2.94	29400	0.05	503
Other organic materials	Epoxy resin B	TS ref# 10237	1.46 E-04	2.94	29400	0.05	503
Others	Epoxy resin modifier	TS ref# 10038	1.46 E-04	2.94	29400	0.05	503
Others	Anhydride	TS ref# 10180	1.46 E-04	2.94	29400	0.05	503
Subtotal			4.97 E-03	100.0	1000000	1.71	17096

	Weight (g)	Percentage (%)	PPM
Package Totals	**2.91 E-01**	**100**	**1000000**

ANALOG DEVICES

ADI Proprietary